

## APPENDIX

## Changes to Claims:

The following is a marked-up version of the amended claims:

1. (Amended) A semiconductor apparatus, comprising:

a substrate main body having a delineated mounting surface for mounting the semiconductor device;

a plurality of leads formed on the mounting surface, the plurality of leads radially extending from a peripheral area toward a central area of the substrate main body; and

a plurality of conduction sections each defining at least part of an external terminal; and substantially delineating fabrication alignment, the conduction sections being electrically connected to the leads.

7. (Amended) A semiconductor apparatus, comprising:

a semiconductor device having a plurality of electrodes;

a substrate main body;

a plurality of leads formed on the substrate main body, the plurality of leads radially extending from a peripheral area toward a central area of the substrate main body; and

a plurality of conduction sections formed on the substrate main body; and substantially delineating fabrication alignment, the conduction sections being electrically connected to the leads, and one of the conduction sections defining an external terminal.